

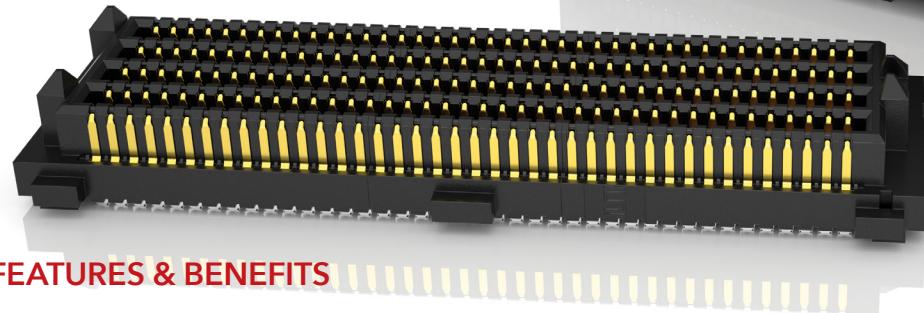
SEARRAYTM 8 mm

ULTRA HIGH-DENSITY, HIGH-SPEED OPEN-PIN-FIELD ARRAYS

(0.80 mm) .0315" PITCH

NRZ
28
Gbps

PAM4
56
Gbps

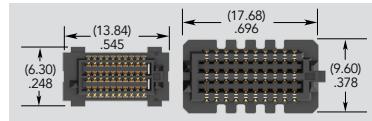


EDGE[®]
RATE
CONTACT

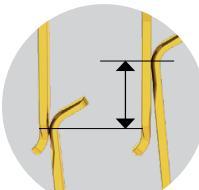
FEATURES & BENEFITS

- 0.80 mm (.0315") pitch grid
- 50% board space savings versus .050" (1.27 mm) pitch arrays
- Performance up to 28 Gbps NRZ/56 Gbps PAM4
- Rugged Edge Rate[®] contact system
- Up to 500 I/Os
- 7 mm and 10 mm stack heights
- Solder charge terminations for ease of processing
- Lower insertion/withdrawal forces
- Analog over Array[™] capable
- Severe Environment Testing qualified (SEAM8/SEAF8); aligns with MIL-DTL-55302.

Visit samtec.com/set

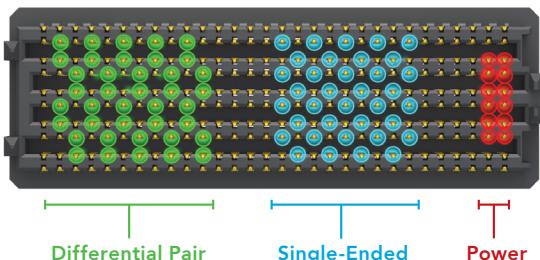


0.80 mm pitch vs. 1.27 mm pitch
(60 pins shown)



(0.95 mm) .037"
Nominal Wipe

MAXIMUM GROUNDING & ROUTING FLEXIBILITY

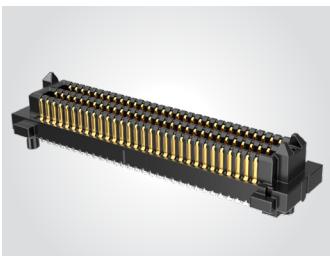


KEY SPECIFICATIONS (SEAF8/SEAM8)

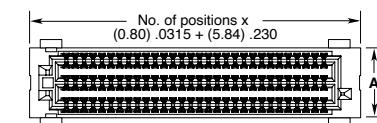
Series	Insulator Material	Contact Material	Plating	Operating Temp Range	Current Rating	Voltage Rating	Lead-Free Solderable
SEAM8					1.3 A per pin (10 adjacent pins powered)	220 VAC/311 VDC	
SEAF8	Black LCP	Copper Alloy	Au or Sn over 50 μ " (1.27 μ m) Ni	-55 °C to +125 °C	1.1 A per pin (10 adjacent pins powered)	240 VAC/339 VDC	Yes
SEAF8-RA							

(0.80 mm) .0315" PITCH • ULTRA HIGH-DENSITY ARRAYS

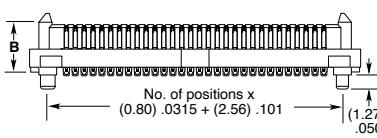
SERIES	NO. PINS PER ROW	LEAD STYLE	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	OPTION	"X"R
SEAM8 Terminal	-10, -20, -30, -40, -50	-S02.0 = 2 mm Body Height (SEAM8 only)	-L = 10 μ " (0.25 μ m) Gold on contact area, Matte Tin on solder tail	-04 -06 -08 -10	-3 = Lead-Free Solder Crimp	-GP = Guide Post (-S02.0 lead style only) (Mates with SEAF8-RA-GP)	Tape & Reel is standard. Leave blank for Tape & Reel.
SEAF8 Socket	-S05.0 = 5 mm Body Height (SEAM8 only)	-05.0 = 5 mm Body Height (SEAF8 only)					-FR = Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)
SEAM8						ALSO AVAILABLE Contact Samtec	
Board Mates: SEAF8						Other platings Tin/Lead solder crimps	
Cable Mates: ESCA							
Standoffs: JSO							



NO. OF ROWS	A
-04	(4.30).169
-06	(6.30).248
-08	(8.30).327
-10	(10.30).406

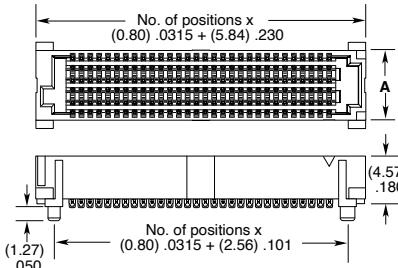
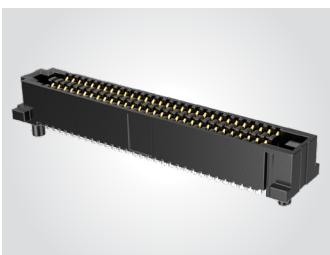


LEAD STYLE	B
-S02.0	(4.54).179
-S05.0	(7.54).297



View complete specifications at: samtec.com?SEAM8

SEAF8
Board Mates: SEAM8
Cable Mates: ESCA
Standoffs: JSO



View complete specifications at: samtec.com?SEAF8

MATED HEIGHTS*

SEAF8 LEAD STYLE	SEAM8 LEAD STYLE	
	-S02.0	-S05.0
-05.0	(7.00) .276	(10.00) .394

*Processing conditions will affect mated height.

Notes:
Polyimide Pick & Place Pad standard without specifying -K.

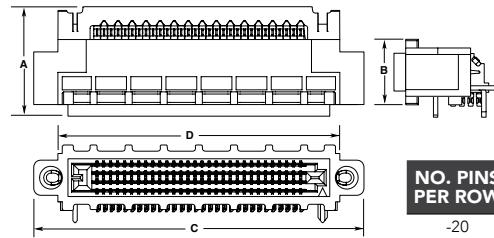
Severe Environment Testing qualified; aligns with MIL-DTL-55302. Visit samtec.com/set

SEAF8	NO. PINS PER ROW	1	PLATING OPTION	NO. OF ROWS	SOLDER TYPE	RA	OPTION	"X"R
	-20, -30, -40, -50		-S = 30 μ " (0.76 μ m) Gold on contact area, Matte Tin on solder tail	-04 (-50 positions only)	-2 = Lead-Free Solder Crimp	-GP = Guide Post Holes		Tape & Reel is standard. Leave blank for Tape & Reel.

SEAF8-RA (Right-angle)
Board Mates: SEAM8
Cable Mates: ESCA



NO. OF ROWS	A	B
-04	(12.48).491	(7.46).294
-08	(16.48).649	(11.46).451
-10	(18.48).728	(13.46).530



Notes:
Some sizes, styles and options are non-standard, non-returnable

View complete specifications at: samtec.com?SEAF8-RA

NO. PINS PER ROW	C	D
-20	(29.62) 1.166	(24.12) 950
-30	(37.62) 1.481	(32.12) 1.265
-40	(45.62) 1.796	(40.12) 1.580
-50	(53.62) 2.111	(48.12) 1.894